

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L4	4559	(257/751,752,753,758,759,761,762,763). CCLS.	USPAT	2006/11/08 08:03
2	IS&R	L5	3338	(257/751,752,753,758,759,761,762,763). CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2006/11/08 08:12
3	BRS	L6	92	(cap passivation barrier diffusion adhesive adhesion film layer) same ((cobalt Co) with (tungsten W) with (phosphorus phosphide P) with (percent percentage "%"))	USPAT	2006/11/08 08:17
4	BRS	L7	253	(cap passivation barrier diffusion adhesive adhesion film layer) same ((cobalt Co) with (tungsten W) with (phosphorus phosphide P) with (percent percentage "%"))	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2006/11/08 08:24
5	BRS	L8	3	CoWP with (percent percentage "%")	USPAT	2006/11/08 08:35
6	BRS	L9	5	CoWP with (percent percentage "%")	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2006/11/08 08:36
7	BRS	L10	4	(cobalt near2 tungsten near2 phosphorus) with (percent percentage "%")	USPAT	2006/11/08 08:37
8	BRS	L11	0	(cobalt near2 tungsten near2 phosphorus) with (percent percentage "%")	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2006/11/08 08:38
9	BRS	L12	158	((cobalt Co) with (tungsten W) with (phosphorus P)) with (percent percentage "%") and (substrate dielectric interconnect interconnecting)	USPAT	2006/11/08 08:39

	Type	L #	Hits	Search Text	DBs	Time Stamp
10	BRS	L13	285	((cobalt Co) with (tungsten W) with (phosphorus P)) with (percent percentage "%") and (substrate dielectric interconnect interconnecting)	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2006/11/08 08:41
11	BRS	L14	3	Co-W-P with (percent percentage "%")	USPAT	2006/11/08 08:44
12	BRS	L15	3	Co-W-P with (percent percentage "%")	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2006/11/08 08:46
13	BRS	L17	8	((CoWP Co-W-P) and (percent percentage "%")).clm.	US-PGPUB	2006/11/08 09:09